

**Features**

- High Density Cell Design for Ultra Low  $R_{DS(on)}$
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

**Maximum Ratings**

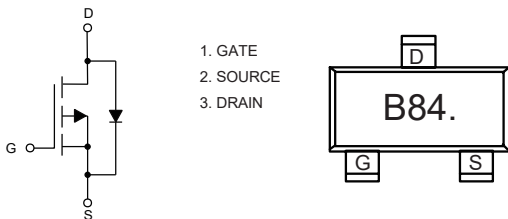
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 306°C/W Junction to Ambient (Note 2)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	-60	V
Gate-Source Voltage	$V_{GS}$	±20	V
Continuous Drain Current	$I_D$	$T_A=25^\circ\text{C}$	-0.16
		$T_A=100^\circ\text{C}$	-0.1
Pulsed Drain Current (Note 3)	$I_{DM}$	-0.64	A
Total Power Dissipation (Note 4)	$P_D$	400	mW

Note:

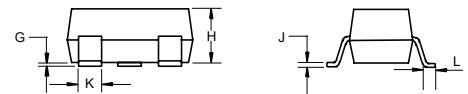
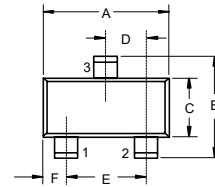
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .
3. Repetitive rating; pulse width limited by max. junction temperature.
4.  $P_D$  is based on max. junction temperature, using junction-ambient thermal resistance.

**Internal Structure and Marking Code**



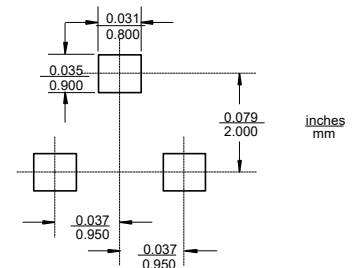
**P-Channel MOSFET**

**SOT-23**



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.110	0.120	2.80	3.04	
B	0.083	0.104	2.10	2.64	
C	0.047	0.055	1.20	1.40	
D	0.034	0.041	0.85	1.05	
E	0.067	0.083	1.70	2.10	
F	0.018	0.024	0.45	0.60	
G	0.0004	0.006	0.01	0.15	
H	0.035	0.043	0.90	1.10	
J	0.003	0.007	0.08	0.18	
K	0.012	0.020	0.30	0.51	
L	0.007	0.020	0.20	0.50	

**Suggested Solder Pad Layout**



**Electrical Characteristics @ 25°C (Unless Otherwise Specified)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-60			V
Gate-Source Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-60V, V_{GS}=0V$			-1	$\mu A$
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.9	-1.3	-2.0	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-0.15A$		2.9	7.8	$\Omega$
		$V_{GS}=-4.5V, I_D=-0.15A$		3.4	9.5	
Gate Resistance	$R_g$	f=1 MHz, Open drain		24		$\Omega$
<b>Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$				-0.16	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=-0.17A$			-1.2	V
Reverse Recovery Time	$t_{rr}$	$I_F=-0.15A, di/dt=100A/\mu s$		23		ns
Reverse Recovery Charge	$Q_{rr}$			13		nC
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=-30V, V_{GS}=0V, f=1MHz$		27		$\mu F$
Output Capacitance	$C_{oss}$			6		
Reverse Transfer Capacitance	$C_{rss}$			3.3		
Total Gate Charge	$Q_g$	$V_{DS}=-30V, V_{GS}=-10V, I_D=-1A$		1.8		nC
Gate-Source Charge	$Q_{gs}$			0.6		
Gate-Drain Charge	$Q_{gd}$			0.8		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS}=-30V, V_{GS}=-4.5V, R_G=2.5\Omega, I_D=-0.15A$		8.6		ns
Turn-On Rise Time	$t_r$			20		
Turn-Off Delay Time	$t_{d(off)}$			15		
Turn-Off Fall Time	$t_f$			77		

**Curve Characteristics**

Fig. 1 - Typical Output Characteristics

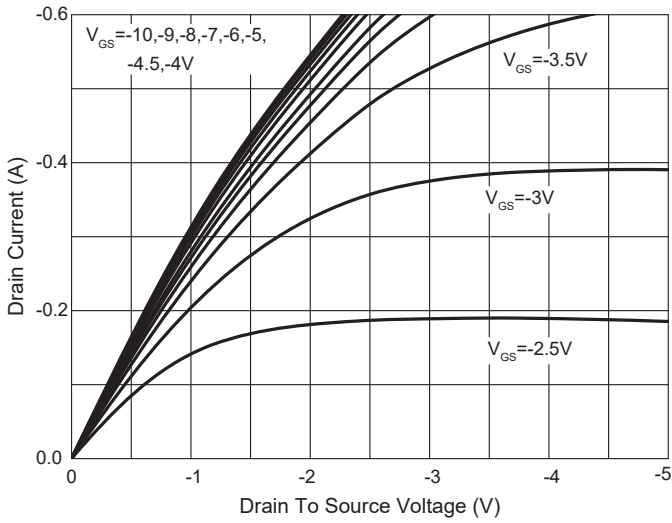


Fig. 2 - Transfer Characteristics

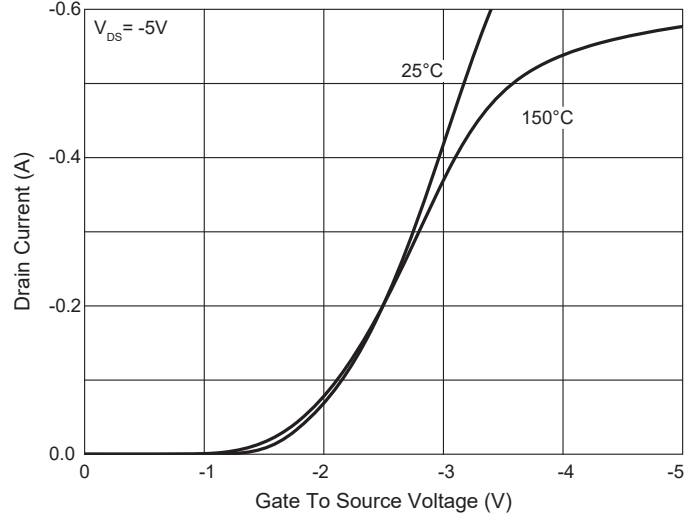


Fig.3- $R_{DS(ON)}$ - $V_{GS}$

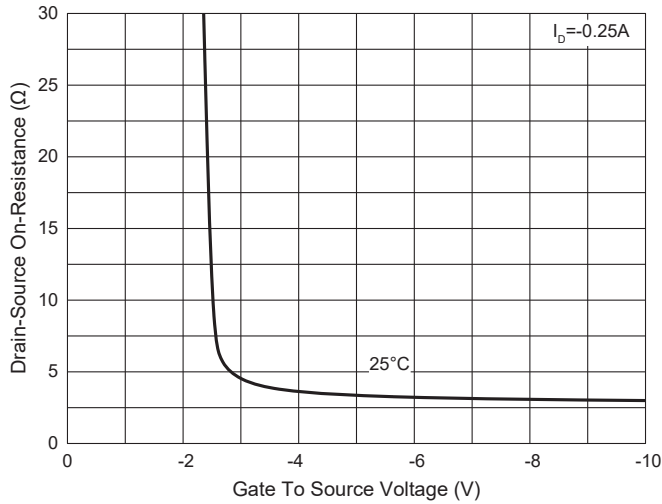


Fig.4- $R_{DS(ON)}$ - $I_D$

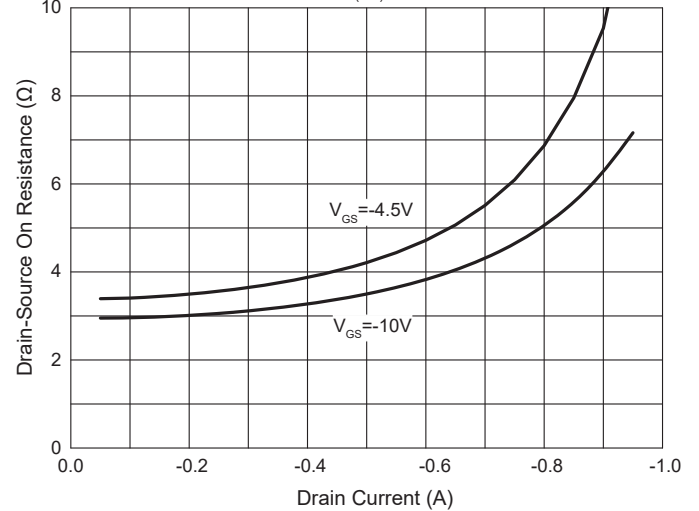


Fig. 5 - Capacitance Characteristics

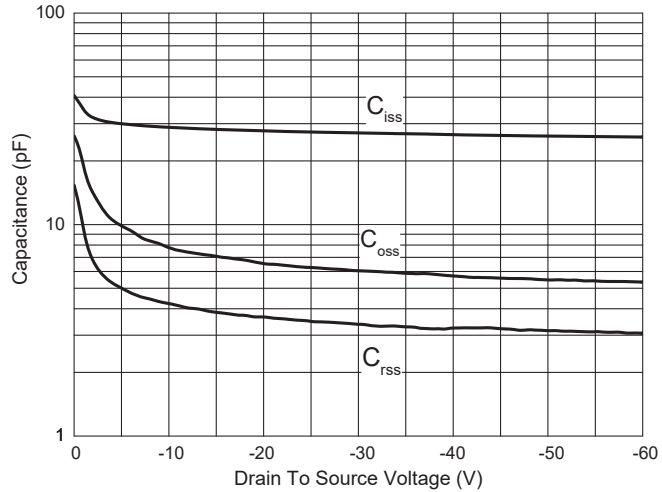
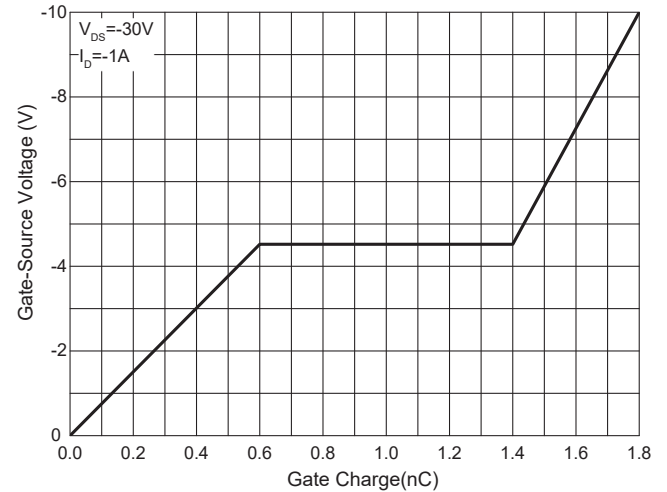


Fig. 6 - Gate Charge



**Curve Characteristics**

Fig. 7 - Normalized Threshold Voltage

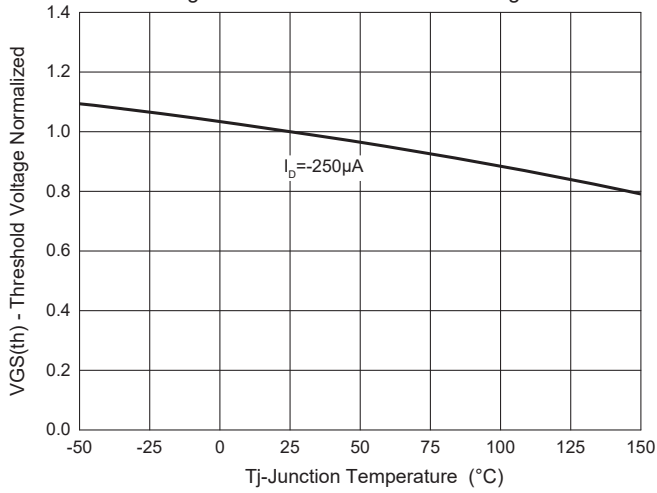


Fig. 8 - Normalized On Resistance Characteristics

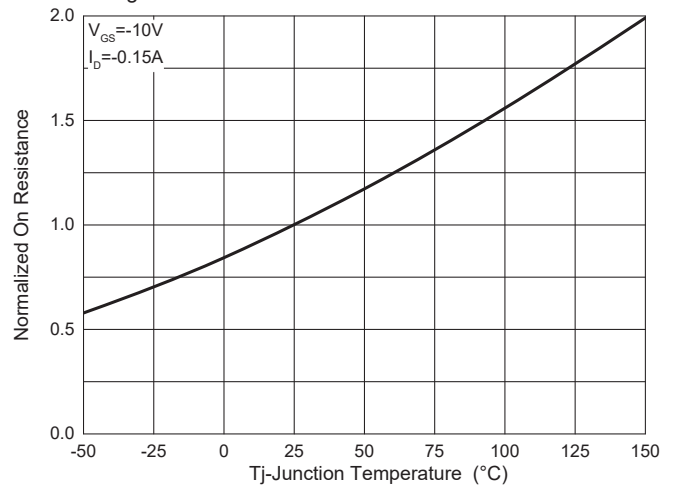


Fig. 9 - I<sub>s</sub> - V<sub>SD</sub>

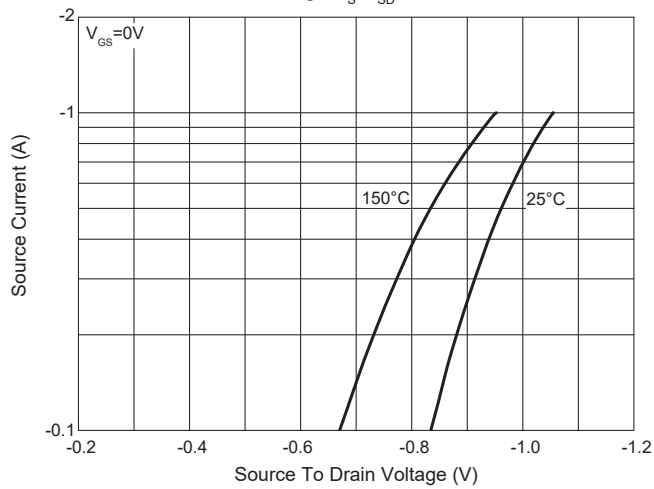


Fig. 10 - Drain Current

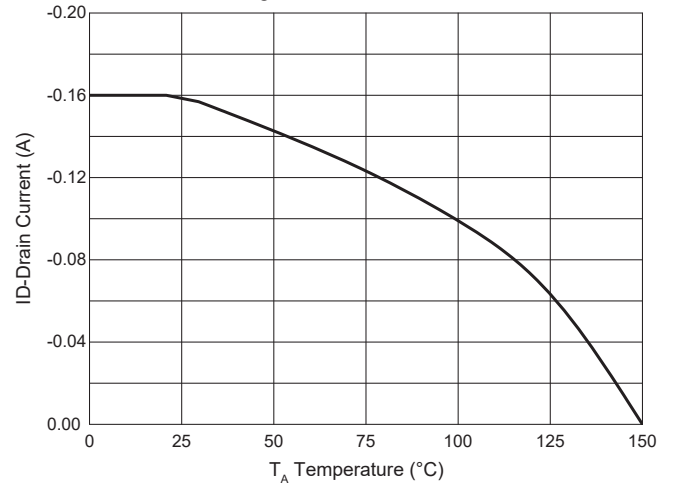
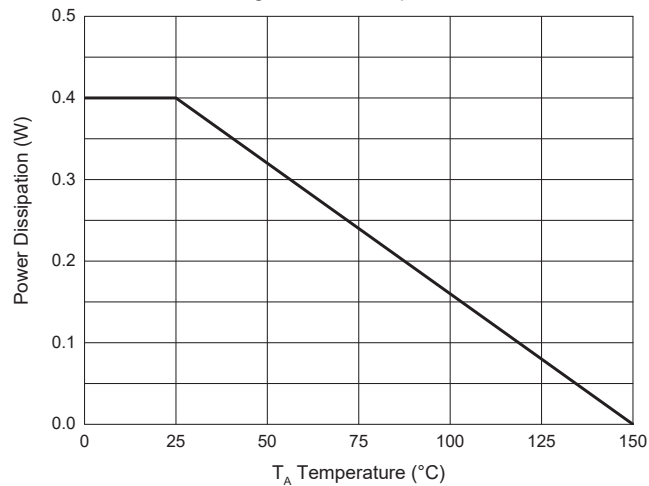


Fig. 11 - PD Dissipation



**Curve Characteristics**

Fig. 12 - Safe Operation Area

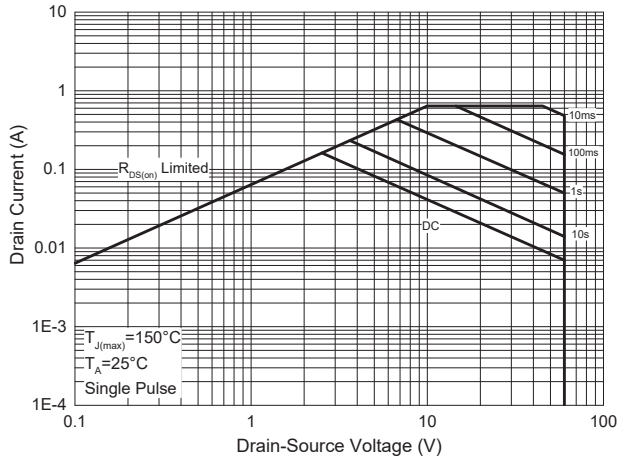
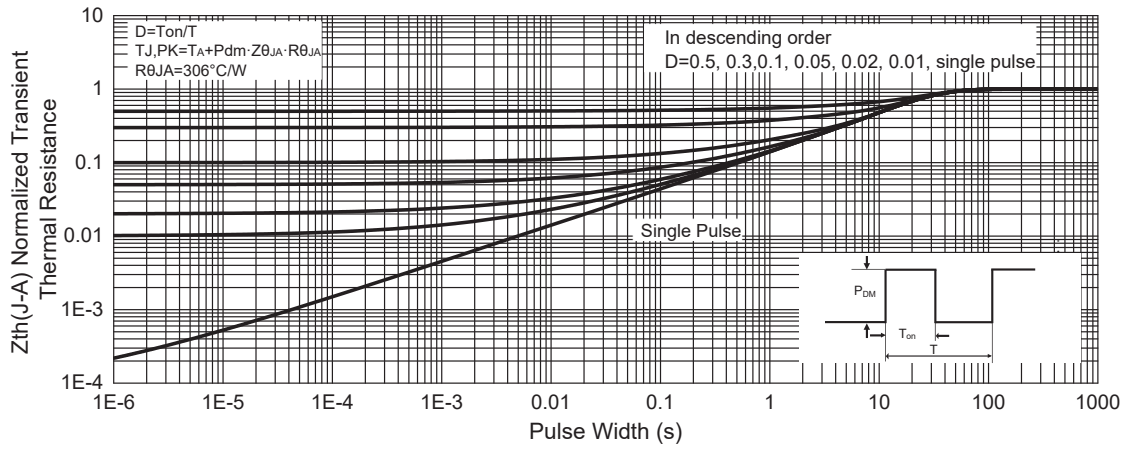


Fig. 13 - Normalized Transient Thermal Impedance



## Ordering Information

Device	Packing
Part Number-TP	Tape&Reel:3Kpcs/Reel

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